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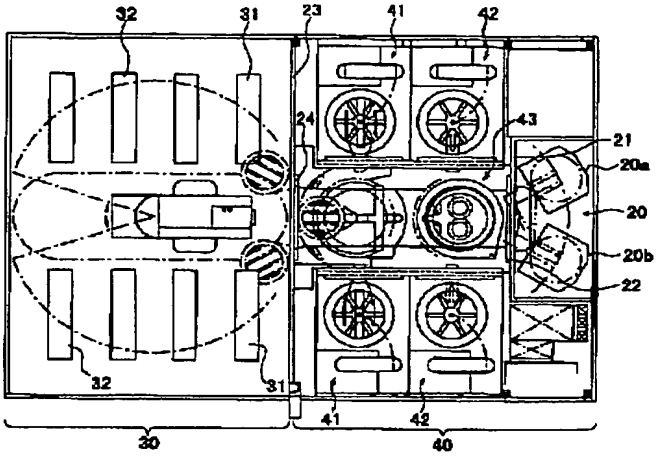
TITLE : APPARATUS FOR PLATING SUBSTRATES



ABSTRACT : PROBLEM TO BE SOLVED: To avoid contamination with particles or mist in a clean room, by placing a cleaning/drying area between an inlet/outlet area and plating area through barriers disposed at the cleaning/drying area, the inlet/outlet area and the plating area.

SOLUTION: An apparatus comprises an inlet-outlet area 20 for transferring wafer cassettes contg. wafers, a plating area 30, and a cleaning/drying area 40 for cleaning and drying the plated wafers. The latter area 40 is disposed between the inlet/outlet area 20 and the plating area 30 through a barrier 21 disposed at the inlet/outlet area 20, the plating area 30 and barrier 23 disposed between the cleaning/drying area 40 and the plating area 30. The barrier 21 has a passage for transferring semiconductor wafers between the inlet/outlet area 20 and the cleaning/drying area 40 with a shutter 22 for opening/closing this passage.

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